

AMENDMENTS TO THE CLAIMS:

Please amend Claims 1, 10, 18, 29, 32, 33, 35 as follows:

1. (presently amended) A method of coating free-standing micromechanical devices, the method comprising:
 - depositing an organic resin coating material on said micromechanical device in sufficient quantity to prevent movement of said micromechanical device, said coating material comprised of at least 35% solids in a solvent, said coating material having a viscosity no greater than 120 centistokes; and
 - curing said coating material.
2. (original) The method of Claim 1, said depositing comprising depositing a coating material having a viscosity of 118 centistokes.
3. (original) The method of Claim 1, said depositing comprising depositing a coating material having a surfactant.
4. (original) The method of Claim 1, said depositing comprising depositing said coating material in a layer thick enough to cover structures on said micromechanical device after the removal of said solvent.
5. (original) The method of Claim 1, comprising:
 - rotating said micromechanical device to distribute said organic coating material.
6. (original) The method of Claim 1, comprising:
 - rotating said micromechanical device at 3000 rpm to distribute said organic coating material.
7. (original) The method of Claim 1, said curing comprising:
 - heating said micromechanical device.
8. (original) The method of Claim 1, said curing comprising:
 - heating said micromechanical device at 100° C.
9. (original) The method of Claim 1, said curing comprising:
 - heating said micromechanical device to a first elevated temperature to remove a majority of said solvent, and then lowering said temperature to remove additional solvent.

10. (presently amended) A method of coating free-standing micromechanical devices, the method comprising:
 - depositing an organic resin coating material on said micromechanical device in sufficient quantity to prevent movement of said micromechanical device, said coating material comprised of at least 35% solids in a solvent, said coating material having a viscosity no greater than 120 centistokes;
 - rotating said micromechanical device to distribute said organic coating material;
 - and
 - curing said coating material.
11. (original) The method of Claim 10, said depositing comprising depositing a coating material having a viscosity of 118 centistokes.
12. (original) The method of Claim 10, said depositing comprising depositing a coating material having a surfactant.
13. (original) The method of Claim 10, said depositing comprising depositing said coating material in a layer thick enough to cover structures on said micromechanical device after the removal of said solvent.
14. (original) The method of Claim 10, comprising:
 - rotating said micromechanical device at 3000 rpm to distribute said organic coating material.
15. (original) The method of Claim 10, said curing comprising:
 - heating said micromechanical device.
16. (original) The method of Claim 10, said curing comprising:
 - heating said micromechanical device at 100° C.
17. (original) The method of Claim 10, said curing comprising:
 - heating said micromechanical device to a first elevated temperature to remove a majority of said solvent, and then lowering said temperature to remove additional solvent.
18. (presently amended) A method of coating free-standing micromechanical devices, the method comprising:

depositing an organic resin coating material on said micromechanical device in sufficient quantity to prevent movement of said micromechanical device, said coating material comprised of at least 40% solids in a solvent, said coating material having a viscosity no greater than 120 centistokes; and
curing said coating material.

19. (original) The method of Claim 18, said depositing comprising depositing a coating material comprised of between 40 and 50% solids.
20. (original) The method of Claim 18, said depositing comprising depositing a coating material comprised of 49% solids.
21. (original) The method of Claim 18, said depositing comprising depositing a coating material having a viscosity of 118 centistokes.
22. (original) The method of Claim 18, said depositing comprising depositing a coating material having a surfactant.
23. (original) The method of Claim 18, said depositing comprising depositing said coating material in a layer thick enough to cover structures on said micromechanical device after the removal of said solvent.
24. (original) The method of Claim 18, comprising:
rotating said micromechanical device to distribute said organic coating material.
25. (original) The method of Claim 18, comprising:
rotating said micromechanical device at 3000 rpm to distribute said organic coating material.
26. (original) The method of Claim 18, said curing comprising:
heating said micromechanical device.
27. (original) The method of Claim 18, said curing comprising:
heating said micromechanical device at 100° C.
28. (original) The method of Claim 18, said curing comprising:
heating said micromechanical device to a first elevated temperature to remove a majority of said solvent, and then lowering said temperature to remove additional solvent.

29. (presently amended) A method of coating free-standing micromechanical devices, the method comprising:
- depositing a solvent layer on said micromechanical device having moveable structures wider than such structures are high;
 - depositing an organic resin coating material on said solvent layer in sufficient quantity to prevent movement of said moveable structures;
 - allowing said organic resin coating material to displace said solvent layer; and
 - curing said organic resin coating material.
30. (original) The method of Claim 29, said depositing an organic resin coating material comprising depositing an organic resin coating material having a viscosity no greater than 120 centistokes.
31. (original) The method of Claim 29, said depositing an organic resin coating material comprising depositing an organic resin coating material having a viscosity of 118 centistokes.
32. (presently amended) The method of Claim 29, said depositing a solvent layer comprising depositing a layer of propylene glycol monomethyl ether PGMEA.
33. (presently amended) The method of Claim 29 ~~4~~, said depositing an organic resin coating material comprising depositing an organic resin coating material comprised of at least 35% solids in a solvent.
34. (original) The method of Claim 29, said depositing a solvent layer comprising depositing a layer of solvent and dissolved organic resin.
35. (presently amended) The method of Claim 29, said depositing a solvent layer comprising depositing a layer of propylene glycol monomethyl ether PGMEA and dissolved organic resin.
36. (original) The method of Claim 29, comprising:
- rotating said micromechanical device to distribute said solvent.
37. (original) The method of Claim 29, comprising:
- rotating said micromechanical device to distribute said organic resin coating material.

38. (original) The method of Claim 29, comprising:
rotating said micromechanical device to remove excess solvent.
39. (original) The method of Claim 29, comprising:
rotating said micromechanical device to remove excess organic resin coating material.
40. (original) The method of Claim 29, said curing comprising:
heating said micromechanical device.
41. (original) The method of Claim 29, said curing comprising:
heating said micromechanical device at 100° C.
42. (original) The method of Claim 29, said curing comprising:
heating said micromechanical device to a first elevated temperature to remove a majority of said solvent, and then lowering said temperature to remove additional solvent.